

MAGIC VIEWS  
VS.  
ACTUAL GDSII/CIF

# Magic Views vs. Actual GDSII/CIF

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- All features in magic are rectangles on a 2-dimensional lambda grid
- However due to either essential requirements of the fabrication technology, or perhaps for optimization purposes, some features are modified when the final chip design is being prepared for fabrication
- The magic technology file specifies all details of the process necessary for design and GDS/CIF
  - In 2017, the EEC116 tech file is located in:  
/software/magic/116/magic/lib/magic/sys/SCN6M\_DEEP.09.tech27
  - Look for commands such as *grow*, *shrink*, *squares*, etc.

# Generation of “Off-Grid” Features

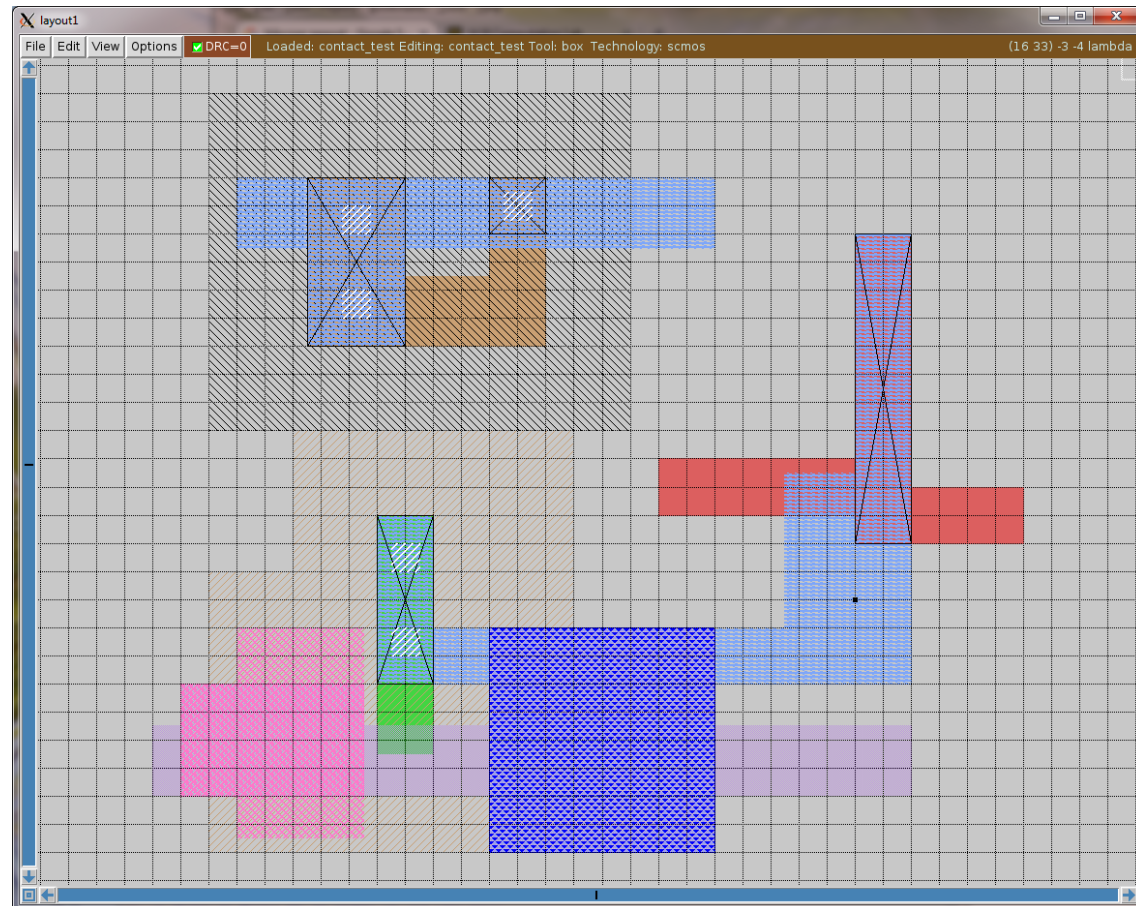
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- As one example, contacts and vias have permitted sizes that are only one specific size
- On the following slides are 4 different examples showing contacts/vias between different materials
- This is also an excellent example of how to optimize the sizing of critical contacts and vias for lower resistance
- Try the “cif see” commands in magic
- Side note: magic uses the **squares** command to solve the problem of generating exact non-lambda-grid sized contacts/vias. The command is in the SCN6M\_DEEP.09.tech27 file and has the following syntax:

**squares** *border size separation*

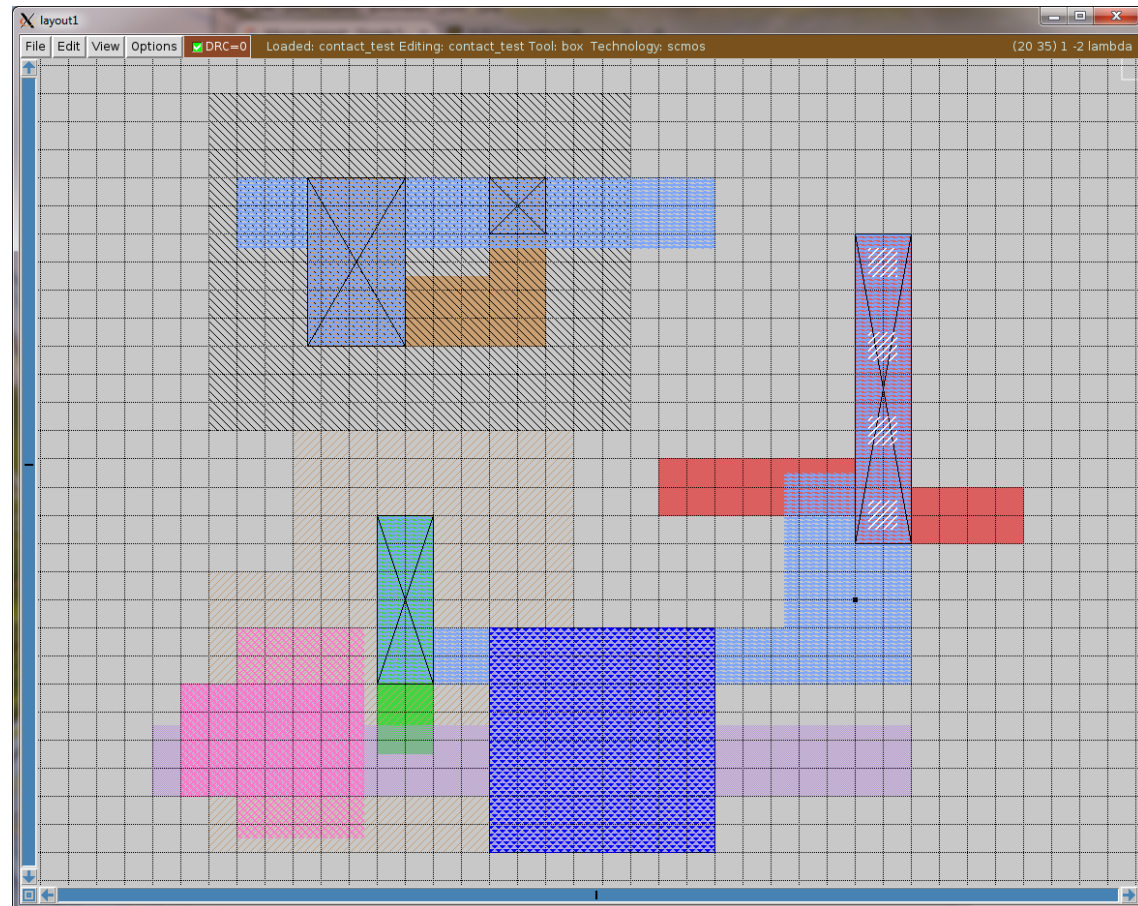
# CCA: Actual NDC and PDC

- The same mask layer is used for both ndiff-m1 contacts and pdiff-m1 contacts—makes sense when you think about it
- **:cif see CCA**
- **:fee cle**
  - “feedback clear”
- **squares 09 18 36**  
(with ndc, pdc)



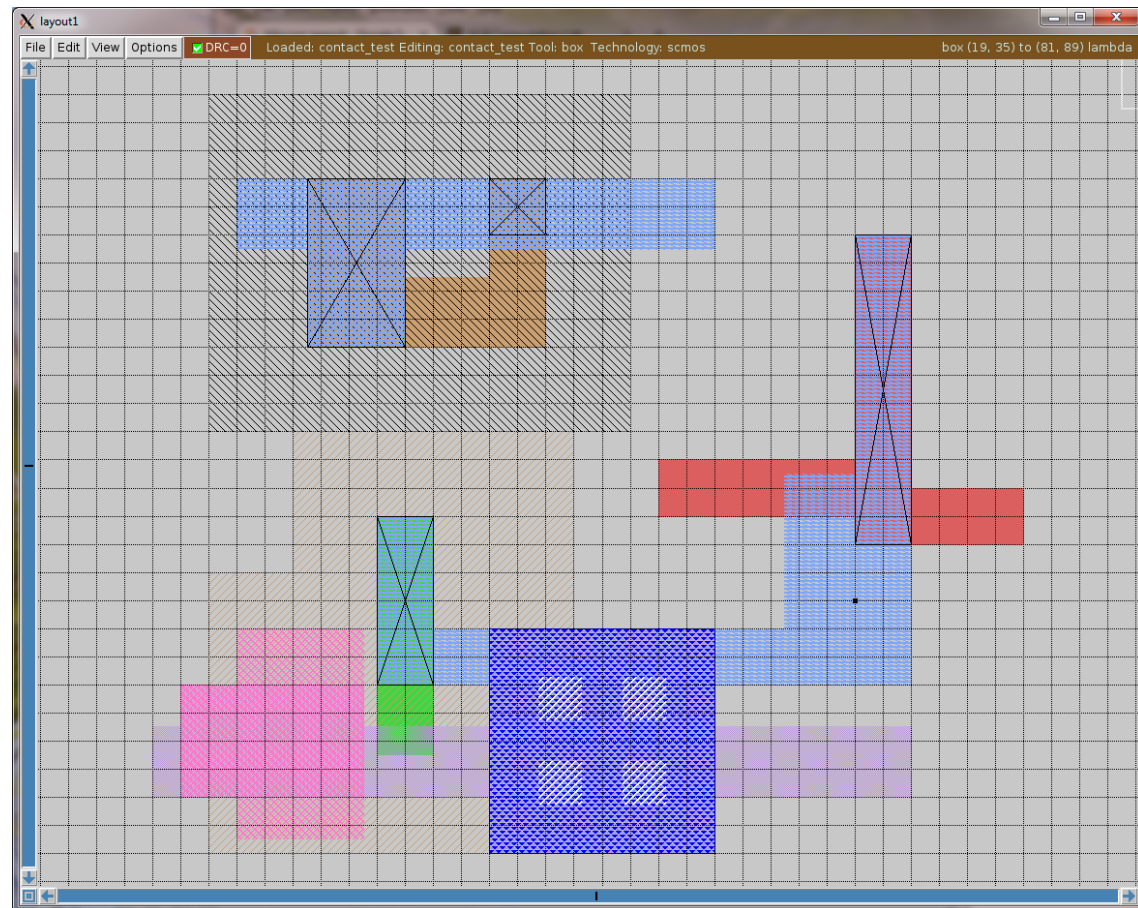
# CCP: Actual Poly-M1 contacts

- Polysilicon-M1 contacts
- **:cif see CCP**
- **:fee cle**
  - “feedback clear”
- **squares 09 18 36**



# CV1: Actual M1-M2 contacts

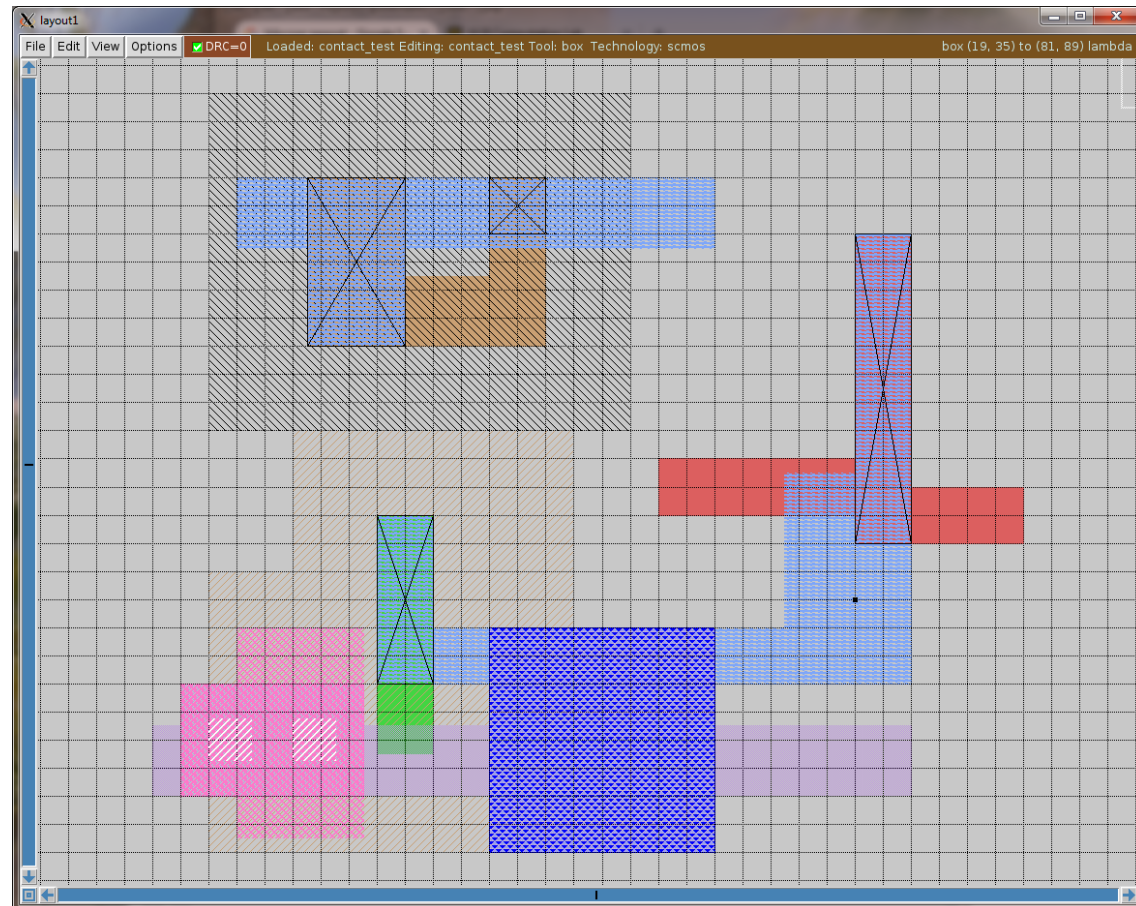
- Metal1-Metal2 contacts
- **:cif see CV1**
- **:fee cle**
  - “feedback clear”
- **squares 09 27 27**





# CV2: Actual M2-M3 contacts

- Metal2-Metal3 contacts
- **:cif see CV2**
- **:fee cle**
  - “feedback clear”
- **squares 09 27 27**



# A Number of Layer Names

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- Search for “cifoutput” in the SCN6M\_DEEP.09.tech27-116 file
  - CWN            nwell
  - CWP            pwell
  - CAA            ndiffusion + pdiffusion + NMOS + PMOS + ndc + pdc + ...
  - CPG            polysilicon
  - CM1—CM6    metal 1 – metal 6
  - CCA            ndiff contacts and pdiff contacts – M1
  - CCP            poly – M1 contacts
  - CV1            M1 – M2 contacts
  - CV2            M2 – M3 contacts